



PK168 (v1.3) January 24,
2013

100% Material Declaration Data Sheet for TQ100 Package

Average Weight: 0.7000g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.037870	5.41
	Silicon	7440-21-3	100.00		0.037870	
Die Attach					0.005040	0.72
	Silver	7440-22-4	78.00		0.003931	
	Epoxy (EP)	Trade Secret	22.00		0.001109	
Mold Compound					0.463960	66.28
	Epoxy Resin (EP)	Trade Secret	9.00		0.041756	
	Phenolic Resin	Trade Secret	7.00	Resin	0.032477	
	Carbon Black	1333-86-4	0.50		0.002320	
	Silica	60676-86-0	82.50		0.382767	
	Bismuth	7440-69-9	Max. 1.00%		0.004640	
Leadframe					0.178850	25.55
	Copper	7440-50-8	98.85		0.176793	
	Chromium	7440-47-3	0.30		0.000537	
	Tin	7440-31-5	0.25		0.000447	
	Zinc	7440-66-6	0.60		0.001073	
Leadframe Plating					0.004550	0.65
	Silver	7440-22-4	100.00		0.004550	
Bond Wire					0.003570	0.51
	Gold	7440-57-5	100.00		0.003570	
External Plating					0.006160	0.88
	Tin	7440-31-5	85.00		0.005236	
	Lead	7439-92-1	15.00		0.000924	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/16/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/29/06	1.2	Updated component descriptions.
01/24/13	1.3	Updated component weights

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